

nexperia.com



Customer Information Notification

CN-202603023I

Issue date: 19 Mar 2026

Effective date: 19 Mar 2026

Dear
productchangenotices@premierfarnell.com,

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



Release of SOT363 Package on STS (Strip-to-Strip) Backend Assembly Platform

Notification information

Reason of Change: As part of Nexperia's continuous improvement and long-term capacity strategy, we are planning the release of the SOT363 package on the STS (Strip-to-Strip) backend assembly platform.

This initiative is not only intended to expand capacity but also to support a gradual transition of SOT363 assembly from the existing BIM (Reel-to-Reel) platform to the STS platform. The introduction of STS technology will enhance manufacturing flexibility, increase throughput, and support future production growth using advanced backend technologies.

The planned release timeframe is Q3 2026. Implementation will be carried out in phases depending on the product type. The corresponding Product Change Notifications (PCNs) will be issued accordingly. Timing and milestones are indicative only.

This advance communication is intended to provide early visibility and to support early customer qualification activities. Additional updates will be shared as implementation and qualification activities progress.

Impact:

- PCNs will be released between May till August 2026.

- Product implementation will occur in multiple waves, and therefore the timing of PCN release, sampling, and documentation vary by product types.

- Material changes include lead frame and molding compound compatible with the STS line. No die change is planned as part of this platform transition. Die changes related to other projects are communicated through separate PCNs and remain unaffected by this notification.

- Relaxed lower specification limits for lead widths. No change to the solder footprint.

- Revised datasheets, including a minor update to the Package Outline Diagram, will be released between May and August 2026.

- No change in product specifications or performance.

- Nexperia will continue to ensure high quality and reliability for all customers.

- PCN samples will become available between April and June 2026.

- PPAP documentation will become available between May and September 2026.

- SOT363 package products will include both “non -Q” and “-Q” portfolio devices.

- In consideration of supply chain continuity, and in contrast to our standard PCN approval timing of 6–12 months, we kindly request customer support for accelerated PCN approval for SOT363 package products.

Instruction:

- To support a timely ramp-up of production capacity, we kindly request our customers cooperation in accelerating the PCN acceptance process for SOT363 packages manufactured on the STS platform. This will allow Nexperia to use the BIM lines mainly

for SOT23 production, helping to avoid potential supply constraints and optimize overall manufacturing capacity.

- Nexperia will continue to invest in increasing SOT363 package capacity, with the goals of improving quality and expanding production capability.

Why do we issue this notification?

Conclusion:

With the release of SOT363 in the STS platform, Nexperia continues to maintain AEC-Q101 Rev. E qualification for “-Q” types and applicable parts and confirms suitability for automotive applications. Nexperia does not expect adverse impact on fit, form, function, or reliability. Customers remain responsible for determining suitability of Nexperia products for the intended use and compliance with applicable standards and customer specifications.

After the PCN acceptance, we reserve all rights to make any technical changes. In terms of specific concerns, please reach out to your local Nexperia Account Team.

Timeline:

Mar 2026: Advanced customer communication about release of SOT363 in STS platform

Apr - Jun 2026: Pre-release of PCN Samples

May - Aug 2026: PCN issuance about release of SOT363 in STS platform

May - Aug 2026: New Revision datasheets available (Updated POD)

May - Sep 2026: Quality documents (PPAP, PSW etc)

Jul - Nov 2026: Implementation of STS

Change

Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

Management summary

Information about upcoming release of SOT363 Package on STS (Strip-to-Strip) Backend Assembly Platform.

Identification of affected products

Changed products can be identified by date code after implementation

Impact

No impact to the product's functionality anticipated

Data sheet revision

A new datasheet will be issued

Additional information

[View Change Notification Online](#)

Remarks

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For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

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